

1.0 INTRODUCTION

This document describes the requirements for procuring the unpackaged integrated circuit die used in the manufacture of P/N OPA676, an Op Amp. All changes and/or substitutions to procured parts are subject to prior approval by Interpoint. This specification is to be used with GEN-008.

2.0 APPLICABLE DOCUMENTS

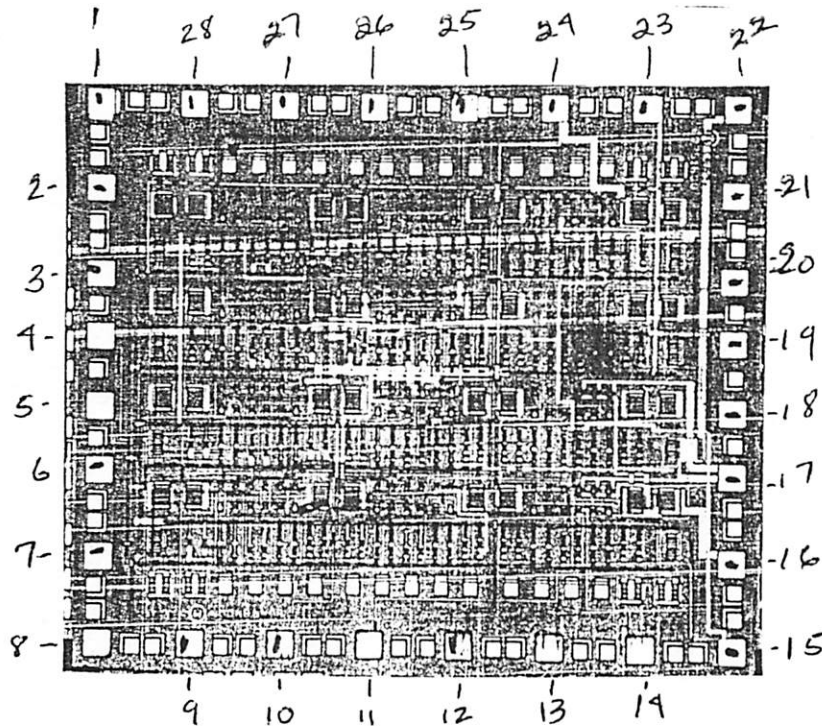
- GEN-008 Integrated Circuit Dice
- QA-029 Element Evaluation Procedure

3.0 REQUIREMENTS

3.1 Mechanical/Physical Characteristics

Each die shall be configured as shown in Figure 1.

Pin No.(Function): 1(TTL Set); 2(-InB); 3(+InB); 4(NC); 5(NC); 6(+InA); 7(-InA); 8(NC); 9(Vos Adj A); 10(Vos Adj B); 11(NC); 12(Comp Cap); 14(NC); 15(+Vcc); 16(+Vcc); 17(Vout); 18(NC); 19(NC); 20(NC); 21(NC); 22(-Vcc); 23(-Vcc); 24(GND); 25(CH Sel In - TTL); 26(ECL<sub>OUT</sub>); 27(CH Sel LOW); 28(CH Sel HIGH)



- NOTES: 1. Mfr. Burr Brown  
 2. Die size .090 x .103 ± .005  
 3. Metallization - Topside: Al; Backside (Vcc): Au or Si

FIGURE 1 - DIE CONFIGURATION

**interpoint**

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SIZE <b>A</b>	CAGE NO. <b>50821</b>	DRAWING NO. 84760	REV B
SCALE		SHEET 2 OF 5	

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